

## CLAIMS

1. A producing method of a semiconductor device, characterized by including a step (b) in which a thermosetting resin is baked at a temperature higher than a resin sealing temperature of a step (a), after the step (a) in which the thermosetting resin is thermally cured to seal a semiconductor chip with the resin.
2. A producing method of a semiconductor device described in claim 1, characterized in that the (b) step is a step in which the curing of the thermosetting resin is advanced.
3. A producing method of a semiconductor device described in claim 1, characterized in that the (b) step is performed at 220-260°C.
4. A producing method of a semiconductor device described in claim 1, characterized by further including a step (c) in which a characteristic of the semiconductor chip is inspected, after said step (b).
5. A producing method of a semiconductor device described in claim 1, characterized in that the semiconductor chip is a semiconductor chip including an integrated circuit.
6. A producing method of a semiconductor device described in claim 1, characterized in that said step (a) is performed through a transfer molding process.
7. A producing method of a semiconductor device described in claim 1, characterized in that said step

(a) is performed through a potting process.

8. A producing method of a semiconductor device, characterized by including

a (a) step in which a thermosetting resin is thermally cured to seal a semiconductor chip with the resin,

a step (b) in which the thermosetting resin is baked at a temperature not more than a resin sealing temperature in the step (a) after said step (a),

a step (c) in which the thermosetting resin is baked at a temperature higher than the resin sealing temperature in the step (a) after said step (b), and

a step (d) in which a characteristic of the semiconductor chip is inspected after said step (c).

9. A producing method of a semiconductor device, characterized by including

a (a) step in which a thermosetting resin is thermally cured to seal a semiconductor chip and a lead electrically connected to an electrode of a main surface of the semiconductor chip with the resin,

a step (b) in which the thermosetting resin is baked at a temperature higher than the resin sealing temperature in the step (a) after said step (a), and

a step (c) in which a characteristic of the semiconductor chip is inspected after said step (b).

10. A producing method of a semiconductor device described in claim 9, characterized in that the electrode of the semiconductor chip is electrically

connected to the lead through a bonding wire.

11. A producing method of a semiconductor device described in claim 9, characterized in that the lead is adhesively fixed to the main surface of the semiconductor chip.

12. A producing method of a semiconductor device described in claim 9, characterized in that the lead is arranged at a periphery of the semiconductor chip.

13. A producing method of a semiconductor device described in claim 9, characterized in that the electrode of the semiconductor chip is electrically connected to the lead through a protruding electrode.

14. A producing method of a semiconductor device, characterized by including

a (a) step in which a thermosetting resin is cured to seal with the resin the semiconductor chip mounted on a wiring substrate,

a (b) step in which the thermosetting resin is baked at a temperature higher than the resin sealing temperature in the step (a) after the step (a), and

a step (c) in which a characteristic of the semiconductor chip is inspected after the step (b).

15. A producing method of an electronic apparatus, characterized by including

a step of preparing a semiconductor device produced by a producing method including a step in which, after a step in which a thermosetting resin is cured to seal a semiconductor chip with the resin and

before a step in which a characteristic of the semiconductor chip is inspected, the thermosetting resin is baked at a temperature higher than the resin sealing temperature in said resin sealing step, and

a step in which the semiconductor device is mounted on a substrate with a solder.

16. A producing method of an electronic apparatus described in claim 15, characterized in that the mounting step is performed with Pb-free solder.